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PATENT

REEL: 015437 FRAME: 0803

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.	
1. Name of conveying party(ies): Chao-Hsiung Wang, Denny Tang, Wen-Chin Lin and Li-Shyue Lai	2. Name and address of receiving party(ies) Name: <u>Taiwan Semiconductor Manufacturing</u> Internal Address: <u>Co., Ltd.</u>
Additional name(s) of conveying party(les) attached?	
3. Nature of conveyance: ✓ Assignment ✓ Assignment ✓ Security Agreement ✓ Other	Science Based Incustrial Fairs, Listin-Chu
	City: TaiwanState:Zip; ROC 300-77
Execution Date:	Additional name(s) & address(es) attached? Yes 🖌 No
A. Patent Application No.(\$) 10/681,541	7. Total fee (37 CFR 3.41)\$40.00
Duane Morris LLP Street Address:One Market Street Spear Tower, Suite 2000 City:_San Francisco State:_CA_Zip:_94105-110	8. Deposit account number: 04-1679
DO	NOT USE THIS SPACE
9. Signature. Howard Chen, Reg. No. 46,615 Name of Person Signing	Kong Chan 12/8/04 Signature
Total number of pages including cover sheet, attachments, and documents: Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 2(231	

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EXPRESS MAIL LABEL NO. EV 306257175 US

Attorney Docket No.: N1085-00223 [TSMC2003-0416]

ASSIGNMENT AND AGREEMENT

For value received, we, Chao-Hsiung Wang, Denny Tang, Wen-Chin Lin, and LI-Shyue Lai, hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to SYSTEM AND METHOD FOR PASSING HIGH ENERGY PARTICLES THROUGH A MASK described in an application for Letters Patent of the United States and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection. including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and 10 invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1 Dated: $\frac{7}{25-0}$

Chao-Hsing Wang/

Residence: FS-1, xb29. 6 Jian Zhong 1st Rood. Hornchu. 300, Taiwan

Inventor No. 2 Dated: <u>- 9/27 - 03 -</u> Denny Tang 20407 Curningham PR Scintoga CA 95070 Residence:

Inventor No. 3 Dated: <u>9/-9 - 07</u> Wen-Und Con-

Residence:

288. + F-2. Park Road, Hsin-Chn, Taiwan, R.O.C.

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Inventor No. 4 Dated: $\frac{9/39 - 0}{2}$

<u>Li-Shyue Fai</u> Li-Shyue Lai

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Residence:

10F., No.5, Lane 371, Jhong jheng E. Rd., Jhubei City, Hsinchu, 202 , Taiwan, .

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